BOARD TITLE: PAINEL_MEB **REVISIONS DESCRIPTION: AUTHOR: CCB** 1 00 - Initial revision - Jun/4/2016 **CODE NUMBER: REVISION: 1 00** LAYER STACKUP: **TOP & BOTTOM: SIGNAL + GND PLANE GENERAL NOTES:** 1. LAMINATE SPECIFICATIONS: 4. SILKSCREEN MASK: - TOTAL THICKNESS: 1.6 mm +/- 0.2 mm - WHITE (THERMAL CURE EPOXY) - LAYER NUMBERS: 2 5. SOLDER MASK: - Cu THICKNESS (FINISHED): 1 oz / 1 oz - BOTH SIDES - RAW MATERIAL: FR-4 - GREEN EPOXY THERMAL CURE OR PHOTO IMAGEABLE - TG MIN.: 150 °C - IONIC CONTAMINATION AFTER SOLDERING: 14 ug NaCI / in2 MAX. - TD MIN.: 310 °C - COVER VIAS WITH SOLDER MASK ON BOTH SIDES 2. HOLE CHARACTERISTICS: **6. SPECIFIED STANDARDS:** - PLATED HOLE TOLERANCE: +/- 0.1 mm - IPC-6011 CLASS 2 / IPC-6012 CLASS 2 / IPC-A-600 CLASS 2 - NON PLATED HOLE TOLERANCE: +/- 0.1 mm 7. ADDITIONAL NOTES: - DISPLACEMENT: 0.1 mm MAX. - DIMENSIONAL TOLERANCE: +/- 0.2 mm - Cu THICKNESS ON HOLE: 20 um + SnPb MIN. - ELECTRICAL TESTS ARE MANDATORY 3. FINISHING: - GERBER MODIFICATIONS ARE ONLY ALLOWED - HOT AIR SOLDER LEVELING (HASL) - SnPb WITH EXPLICIT AUTHOR / RESPONSIBLE AUTHORIZATION PAINEL_MEB - 1_00 - 2016/JUN MAUÁ IMT - INSTITUTO MAUÁ DE TECNOLOGIA FD3 NSEE FD2

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